

DMN2005K

N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

Features

- Low On-Resistance
- Very Low Gate Threshold Voltage, 0.9V Max.
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- **ESD Protected Gate**

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Ordering & Date Code Information: See Below
- Weight: 0.008 grams (Approximate)

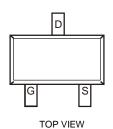




SOT23

Protection

Drain



TOP VIEW

Equivalent Circuit

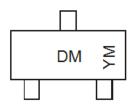
Ordering Information (Note 4)

ĺ	Part Number	Case	Packaging
	DMN2005K-7	SOT23	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 - 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



DM = Product Type Marking Code YM = Date Code Marking Y = Year (ex: E = 2017)M = Month (ex: 9 = September)

Date Code Key

Year	2	006	-	2017	2018	2019	2020	2021	2022	2023	2024	2025
Code		Т	-	Е	F	G	Н	l	J	K	L	М
Month	Jan	Fe	eb M	ar Ap	r May	/ Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	2 3	3 4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	20	V	
Gate-Source Voltage		V _{GSS}	±10	V
Drain Current Per Element (Note 5)	Continuous Pulsed (Note 6)	I _D	300 600	mA

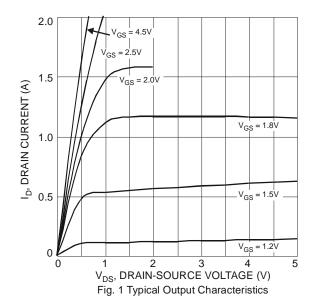
Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

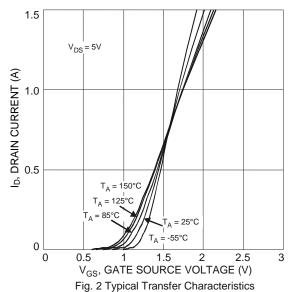
Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_{D}	350	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

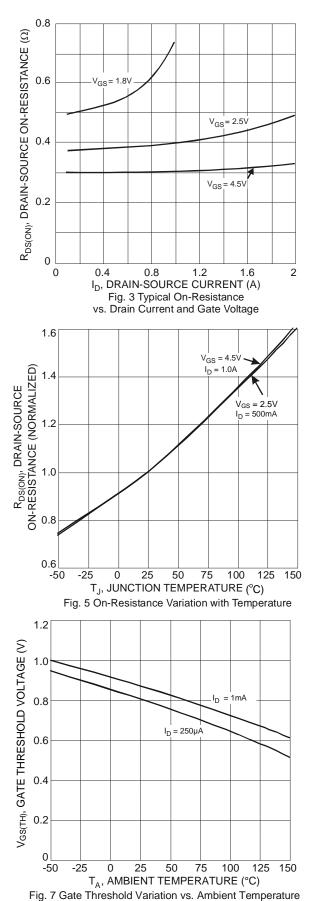
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 100\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	10	μA	$V_{DS} = 17V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±5	μA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	0.53	_	0.9	V	$V_{DS} = V_{GS}$, $I_D = 100\mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	0.55 0.4	3.5 1.7	Ω	$V_{GS} = 1.8V, I_D = 200mA$ $V_{GS} = 2.7V, I_D = 200mA$	
Forward Transfer Admittance	Y _{fs}	40	_		mS	$V_{DS} = 3V, I_{D} = 10mA$	
Diode Forward Voltage	V_{SD}		0.7	1.4	V	$V_{GS} = 0V, I_{S} = 200mA$	

- 5. Device mounted on FR-4 PCB.
- 6. Pulse width ≤10µS, Duty Cycle ≤1%.
 7. Short duration pulse test used to minimize self-heating effect.









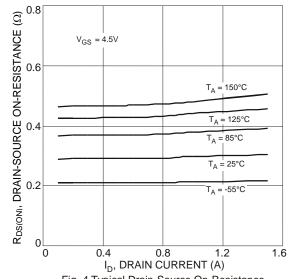


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

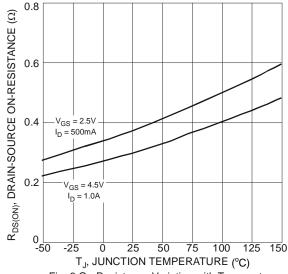


Fig. 6 On-Resistance Variation with Temperature

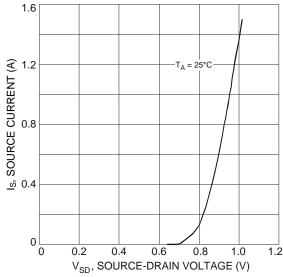
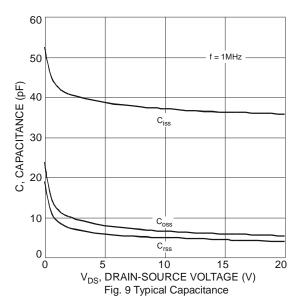


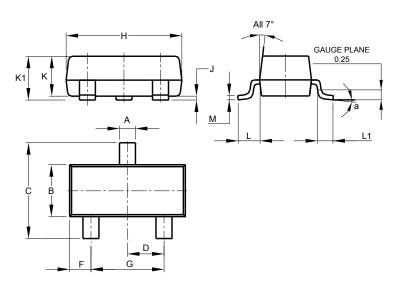
Fig. 8 Diode Forward Voltage vs. Current





Package Outline Dimensions

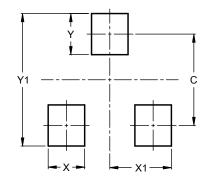
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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